## **AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

Claims 1-61 (Canceled).

62. (Currently Amended) A nitride semiconductor light emitting device comprising;

a substrate,

a first nitride semiconductor layer having an impurity concentration <u>less than</u> within-1  $\times$  10<sup>17</sup>/cm<sup>3</sup>, said first nitride semiconductor layer being a single layer,

a second nitride semiconductor layer having an n-type electrode, said second nitride semiconductor layer being a single layer,

a third nitride semiconductor layer having an impurity concentration <u>less</u>

<u>than within-1 X 10<sup>17</sup>/cm<sup>3</sup></u>, said third nitride semiconductor layer being a super lattice layer of InGaN layers and GaN layers, and

<u>a separate and distinct</u> an-active layer where electrons and holes are combined.

63. (Previously Presented) The nitride semiconductor light emitting device according to claim 62;

wherein said second nitride semiconductor layer is made of GaN or AlGaN and said second nitride semiconductor layer includes Si as an n-type impurity.

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64. (Previously Presented) The nitride semiconductor light emitting device according to claim 62;

wherein said first nitride semiconductor layer is made of GaN or AlGaN.

65. (Previously Presented) The nitride semiconductor light emitting device according to claim 62;

wherein said second nitride semiconductor layer has an carrier concentration more than 3 X 10<sup>18</sup>/cm<sup>3</sup>.

66. (Previously Presented) The nitride semiconductor light emitting device according to claim 62;

wherein said second nitride semiconductor layer has a resistivity less than  $8 \times 10^{-3}$  ohm  $^{\circ}$  cm.

67. (Previously Presented) The nitride semiconductor light emitting device according to claim 62;

further comprising a buffer layer between said substrate and said first nitride semiconductor layer.

68. (Previously Presented) The nitride semiconductor light emitting device according to claim 62;

wherein said first nitride semiconductor layer has a thickness within

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a range of from 0.1 to 20 µm.

69. (Previously Presented) The nitride semiconductor light emitting device according to claim 62;

wherein said second nitride semiconductor layer has a thickness within a range of from 0.1 to 20  $\mu m,\,$ 

70. (Currently Amended) A nitride semiconductor light emitting device comprising:

a substrate,

a first nitride semiconductor layer having an impurity concentration

<u>less than</u> within-1 X 10<sup>17</sup>/cm<sup>3</sup>, said first nitride semiconductor layer being a single layer,

a second nitride semiconductor layer having an n-type electrode, said second nitride semiconductor layer being a single layer,

a third nitride semiconductor layer being a super lattice layer of GaN layers, and

<u>a separate and distinct</u> <del>an</del>-active layer where electrons and holes are combined.

71. (Previously Presented) The nitride semiconductor light emitting device according to claim 70;

wherein said second nitride semiconductor layer is made of GaN or AlGaN and said second nitride semiconductor layer includes Si as an n-type impurity.

72. (Previously Presented) The nitride semiconductor light emitting device according to claim 70;

wherein said first nitride semiconductor layer is made of GaN or AlGaN

73. (Previously Presented) The nitride semiconductor light emitting device according to claim 70;

wherein said second nitride semiconductor layer has an carrier concentration more than 3 X 10<sup>18</sup>/cm<sup>3</sup>.

74. (Previously Presented) The nitride semiconductor light emitting device according to claim 70;

wherein said second nitride semiconductor layer has a resistivity less than 8  $\times$  10<sup>-3</sup> ohm  $\cdot$  cm.

75. (Previously Presented) The nitride semiconductor light emitting device according to claim 70;

further comprising a buffer layer between said substrate and said first nitride semiconductor layer.

76. (Previously Presented) The nitride semiconductor light emitting device according to claim 70;

wherein said first nitride semiconductor layer has a thickness within a range of from 0.1 to 20  $\mu m$ ,

77. (Previously Presented) The nitride semiconductor light emitting device according to claim 70;

wherein said second nitride semiconductor layer has a thickness within a range of from 0.1 to 20 µm.

78. (Previously Presented) The nitride semiconductor light emitting device according to claim 70;

wherein said third nitride semiconductor layer being a super lattice layer of undoped GaN layers and Si doped GaN layers.

79. (Previously Presented) The nitride semiconductor light emitting device according to claim 78;

wherein said Si doped GaN layers are doped with Si to 1x10<sup>19</sup>/cm<sup>3</sup>.

80. (Previously Presented) The nitride semiconductor light emitting device according to claim 78;

wherein said undoped GaN layers have a thickness of 75Å and Si doped GaN layers have a thickness of 25Å.

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81. (Previously Presented) The nitride semiconductor light emitting device according to claim 78;

wherein said third nitride semiconductor layer has a thickness of 600Å.